

## B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (Currently Amended) A **plating** solution comprising ionic Fe, ionic Pt, and a complex agent at a molar ratio of the ionic Fe to the ionic Pt ranging from 0.75 to 3, wherein the solution is such that a composition consisting of Fe and Pt or Fe, Pt, and Cu is deposited when plating using the solution.

2. (Currently Amended) The **plating** solution according to claim 1, wherein the complex agent contains tartrate ions or citrate ions.

3. (Currently Amended) The **plating** solution according to claim 1, wherein the concentration of the ionic Fe ranges from 0.005 mol/L to 0.1 mol/L.

4. (Currently Amended) The **plating** solution according to claim 1, wherein the **plating** solution has a pH ranging from 5.0 to 10.5.

5. (Currently Amended) The **plating** solution according to claim 1, wherein the ionic Fe and the ionic Pt form a double complex constituted of an Fe complex and a Pt complex.

6. (Currently Amended) The plating solution according to claim 1, wherein the plating solution contains ionic Cu and a complex agent for the ionic Cu.

7. (Withdrawn) A process for producing a structure comprising steps of:

providing an electrode and an object to be plated in a vessel containing a plating solution set forth in claim 1, and

plating the object with a magnetic material containing FePt from the plating solution by applying voltage to the electrode to form a structure.

8. (Withdrawn) A process for producing a structure, wherein the structure formed in claim 7 is heat-treated further at a temperature ranging from 450°C to 750°C.

9. (Withdrawn) A process for producing a structure, wherein the structure set forth in claim 7 is heat-treated further in the presence of hydrogen.

10. (Withdrawn) The process for producing a structure according to claim 7, wherein the object to be plated is a structure having holes, and the step of plating the object to form the structure is deposition of the magnetic material containing FePt into the holes.

11. (Withdrawn) An apparatus comprising a plating solution as set forth in claim 1, a vessel for holding the plating solution, and electrodes, for conducting plating by application of a voltage to the electrodes.